

175N100A

100V 3.3mΩ N-Channel Power MOSFET

DESCRIPTION:

- Ultra-low RDS(ON)
- Low Gate Charge
- 100% UIS Tested, 100% Rg Tested
- Pb-Free Lead Plating
- RoHS compliant

Vds	100V
VGS(th)_Typ	3.2V
I _D @ V _{GS} =10V	175 A
R _{DS(on)_Typ} @ V _{GS} =10V	3.3 mΩ

TYPICAL APPLICATIONS:

- · Power Management in Telecom., Industrial Automation, CE
- Current Switching in DC/DC & AC/DC (SR) Sub-systems
- Motor Driving in Power Tool, E-vehicle, Robotics

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MAXIMUM RATINGS (at T_A = 25 °C, unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Drain-Source Voltage		V _{DS}	100	V
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current ⁽¹⁾	Tc=25℃ Tc=100℃	I _D	175 110	А
Pulsed Drain Current ⁽²⁾		I _{DM}	700	А
Avalanche Energy ⁽³⁾		E _{AS}	600	mJ
Power dissipation ⁽⁴⁾	Tc=25℃ Tc=100℃	P _D	250 100	w
Junction & Storage temperature Range		T _J , T _{STG}	-55~+150	°C

Notes : 1. Computed continuous current assumes the condition of TJ_Max while the actual continuous current depends on the thermal & electro-mechanical application board design...

2. This single-pulse measurement was taken under $T_{J_Max} = 150$ °C. 3. E_{AS} of 600mJ is based on starting $T_J = 25$ °C, L = 0.5mH, I_{AS} = 49.7A, V_{GS} = 10V, V_{DD} = 50V; 100% test

at L = 0.1mH, I_{AS} =69.6A.

4. The power dissipation PD is based on $T_{J Max} = 150^{\circ}C$.

THERMAL CHARACTERISTICS

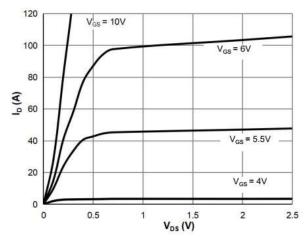
Characteristic	Condition	Symbol	Тур.	Unit
Thermal resistance,	Junction – Ambient Junction - Case	$\begin{array}{l} R_{\theta(j\text{-}A)} \\ R_{\theta(j\text{-}C)} \end{array}$	59 0.42	°C/W

Characteristic	Symbol	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage VGS = 0V, ID = 250uA	V _{(BR)DSS}	100			V
Zero Gate Voltage Drain Current VDS = 80 V, VGS = 0 V Tj=25 $^{\circ}$ C VDS = 80 V, VGS = 0 V Tj=55 $^{\circ}$ C	I _{DSS}			1 5	uA
Gate-Source Leakage Current VGS = ±20V, VDS = 0V	I _{GSS}			±100	nA
Gate-Source threshold voltage VDS = VGS, ID = 250uA	V _{GS(th)}	2.0	3.2	4.0	V
Drain-Source On-State Resistance VGS = 10V, ID = 20A	R _{DS(on)}		3.3	4.0	mΩ
Forward Transconductance VDS = 5V, ID = 20A	g fs		47.8		S
Input capacitance f=1MHz, VDS=50 V, VGS=0 V	C _{iss}		7168		pF
Output capacitance f=1MHz, VDS=50 V, VGS=0 V	C _{oss}		1067		pF
Reverse transfer capacitance f=1MHz, VDS=50 V, VGS=0 V	C _{rss}		36		pF
Gate Resistance f=1MHz, VDS=0 V, VGS=0 V	R _g		2.7		Ω
Total Gate Charge VDS= 50V, ID= 20A,VGS= 10V VDS= 50V, ID= 20A,VGS= 6V	Q _G		104 66		nC
Gate to Source Charge VDS= 50V, ID= 20A,VGS= 0 to 10V	Q _{GS}		39		nC
Gate to Drain Charge VDS= 50V, ID= 20A,VGS= 0 to 10V	Q _{GD}		21		nC
Turn-on delay time VDS=50 V, VGS= 10V, R _L =2.5Ω, R _{GEN} =3Ω	td _(ON)		22		ns
Rise time VDS=50 V, VGS= 10V, R _L =2.5Ω, R _{GEN} =3Ω	tr		32		ns
Turn-off delay time VDS=50 V, VGS= 10V, R _L =2.5Ω, R _{GEN} =3Ω	td _(OFF)		62		ns
Fall time VDS=50 V, VGS= 10V, R _L =2.5Ω, R _{GEN} =3Ω	tf		36		ns

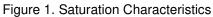
Body Diode

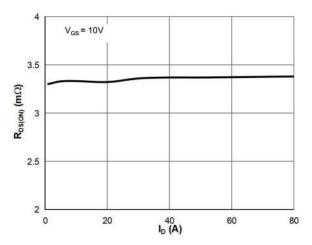
ELECTRICAL CHARATERISTICS (at T_J = 25 °C, unless otherwise specified)

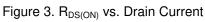
Characteristic	Symbol	Min.	Тур.	Max.	Unit
Diode Forward Voltage VGS = 0V, I_S = 1A	V_{SD}		0.70	1.0	V
Diode Continuous Current, Tc=25 $^{\circ}$ C	I _S			175	V
Revers Recovery Time IF=15A, dIF/dt = 100A/us	Trr		95		ns
Revers Recovery Charge IF=15A, dIF/dt = 100A/us	Qrr		299		nC

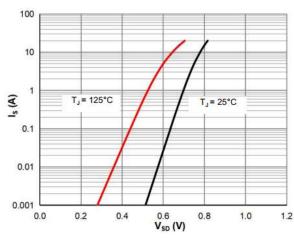


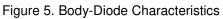
Typical Electrical & Thermal Characteristics











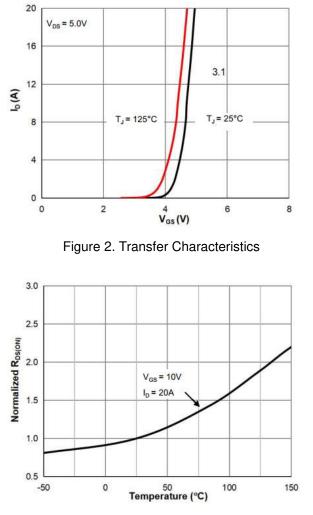


Figure 4. R_{DS(ON)} vs. Junction Temperature

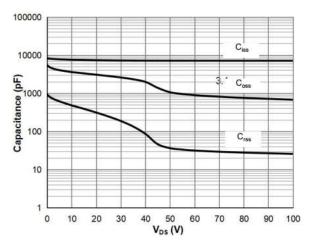
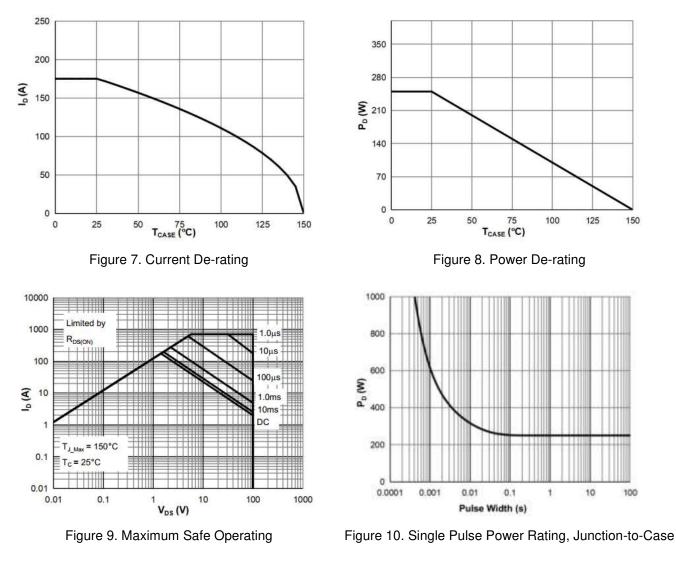


Figure 6. Capacitance Characteristics

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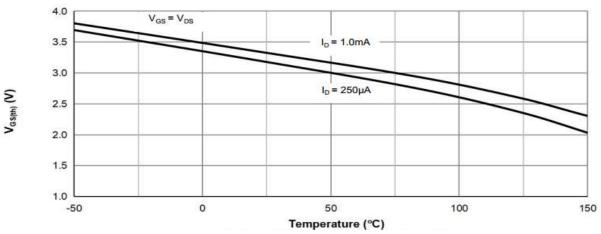


Figure 11. $V_{GS(th)}$ vs. Junction Temperature

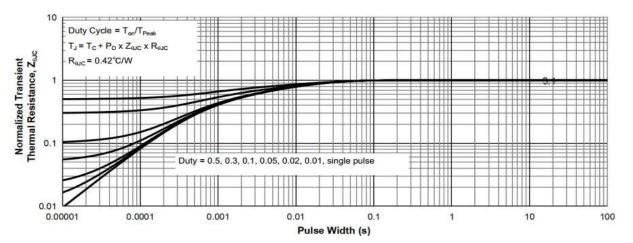
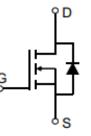
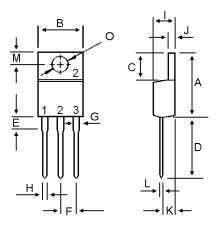


Figure 11. Normalized Maximum Transient Thermal Impedance

Circuit diagram



TO-220AB Package outlines : Dimensions in (mm)



DIM	MILLIMETERS		
DIN	MIN	MAX	
А	14.68	16.20	
В	9.78	10.42	
С	5.02	6.60	
D	13.00	14.62	
E	3.10	4.19	
F	2.41	2.67	
G	1.10	1.67	
Н	0.69	1.01	
	4.22	4.98	
J	1.14	1.40	
K	2.20	3.30	
L	0.28	0.61	
М	2.48	3.00	
0	3.40	4.00	



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